

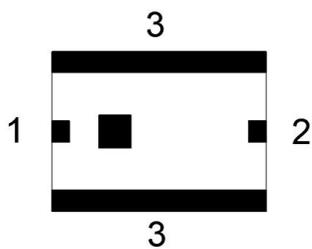
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

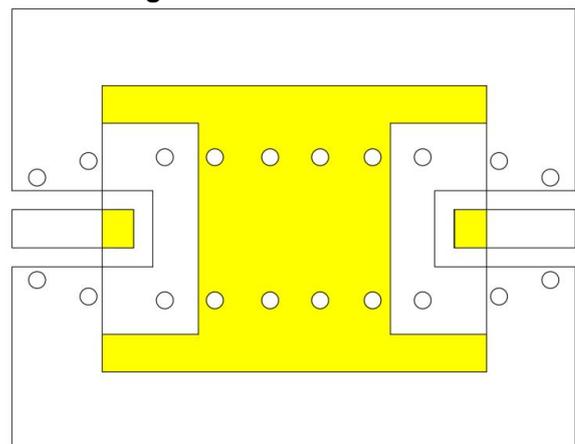
NO.	Parameter	Frequency (MHz)	SPEC		
			Min.	Typ.	Max.
1	Insertion Loss (dB) @25°C	2338~2413			4.0
2	Ripple(dB)	2338~2413			1.0
3	VSWR	2338~2413			2.0
4	Attenuation (dB)	2188	25		
		2488	10		

Construction



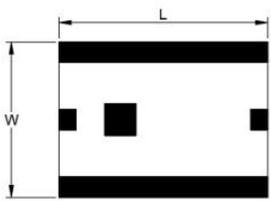
PIN	Connection
1	Input Port
2	Output Port
3	GND

Mounting Considerations

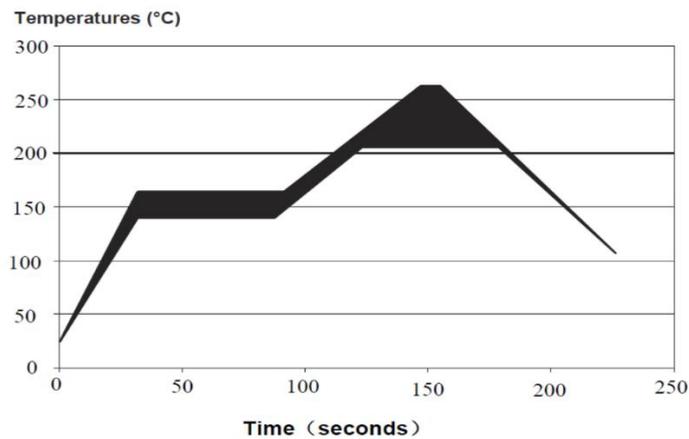


Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
<p style="text-align: center;">Top View</p> 	L	6.00 ± 0.20
	W	4.50 ± 0.20
<p style="text-align: center;">Side View</p> 	T	2.00 max.
<p style="text-align: center;">Bottom View</p> 	A	0.60 ± 0.15
	B	3.32 ± 0.15
	C	1.50 ± 0.15
	D	0.50 ± 0.15

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.